Material Composition Specification

SOIC-16 Case





Device average mass	145 mg
Fluctuation margin	. +/-10%

Component	Material	Material		Cubatanaa		Substance		
		(%wt)	(mg)	Substance	CAS No.	(%wt)	(mg)	(ppm)
active device	doped Si	2.66%	3.86	Si	7440-21-3	2.66%	3.86	26,621
bond wire	gold	0.28%	0.4	Au	7440-57-5	0.28%	0.4	2,759
leadframe	copper	31.38%	45.5	Cu	7440-50-8	31.38%	45.5	313,793
die attach	silver epoxy	0.3%	0.44	Ag	7440-22-4	0.24%	0.35	2,414
				epoxy resin	Proprietary	0.06%	0.09	621
encapsulation	EMC 63.79%	63.79% 92.5	92.5	silica (fused)	60676-86-0	44.9%	65.1	448,966
				epoxy resin	Proprietary	15.86%	23.0	158,621
				Sb ₂ O ₃	1309-64-4	1.24%	1.8	12,414
			TBBA	79-94-7	1.52%	2.2	15,172	
				carbon	1333-86-4	0.28%	0.4	2,759
plating*	tin/lead process 1.5	4 500/	59% 2.3	Sn	7440-31-5	1.34%	1.95	13,448
		1.59%		Pb	7439-92-1	0.24%	0.35	2,414
	matte tin	1.59%	2.3	Sn	7440-31-5	1.59%	2.3	15,862

*For Lead Free plating, add suffix "PB FREE" to part number. For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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